

Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 3)**
- **"Green" Device (Note 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

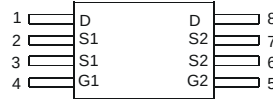
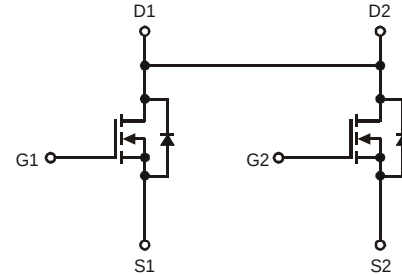
- Case: TSSOP-8L
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram Below
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.039 grams (approximate)



TOP VIEW



BOTTOM VIEW


Top View
Pin Configuration


Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 1)	Steady State	T _A = 25°C	I _D	4.9	A
		T _A = 70°C		3.9	
Pulsed Drain Current (Note 2)			I _{DM}	31	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P _D	0.87	W
Thermal Resistance, Junction to Ambient @T _A = 25°C	R _{θJA}	143	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
1. Device mounted on FR-4 PCB with minimum recommended pad layout.
 2. Repetitive rating, pulse width limited by junction temperature.
 3. No purposefully added lead.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1.0	μA	V _{DS} = 20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.5	-	0.9	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	19	25	mΩ	V _{GS} = 4.5V, I _D = 8.2A
			22	29		V _{GS} = 2.5V, I _D = 3.3A
			28	37		V _{GS} = 1.8V, I _D = 2.0A
Forward Transfer Admittance	Y _{fs}	-	7	-	S	V _{DS} = 10V, I _D = 4A
Diodes Forward Voltage	V _{SD}	-	0.7	0.9	V	I _S = 2.25A, V _{GS} = 0V
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C _{iss}	-	841	-	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	88	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	81	-	pF	
Gate Resistance	R _g	-	1.24	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
SWITCHING CHARACTERISTICS						
Total Gate Charge	Q _g	-	9.6	-	nC	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 8.2A
Gate-Source Charge	Q _{gs}	-	1.4	-	nC	
Gate-Drain Charge	Q _{gd}	-	2.1	-	nC	
Turn-On Delay Time	t _{D(on)}	-	7.8	-	ns	V _{DD} = 10V, V _{GS} = 4.5V, R _L = 10Ω, R _G = 6Ω
Turn-On Rise Time	t _r	-	21.1	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	38.6	-	ns	
Turn-Off Fall Time	t _f	-	10.1	-	ns	

Notes: 5. Short duration pulse test used to minimize self-heating effects.
6. Guaranteed by design. Not subject to production testing.

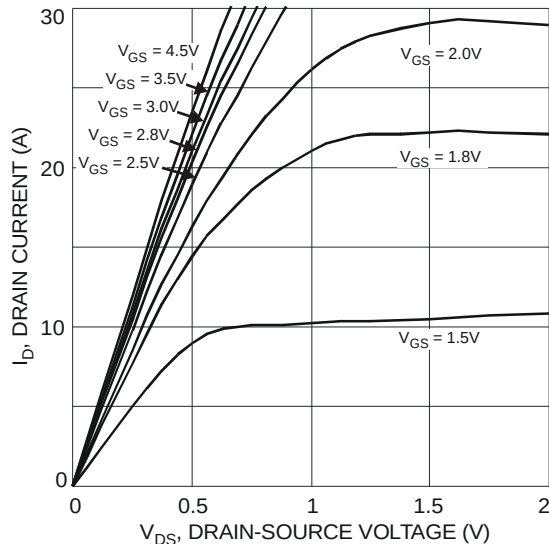


Fig. 1 Typical Output Characteristics

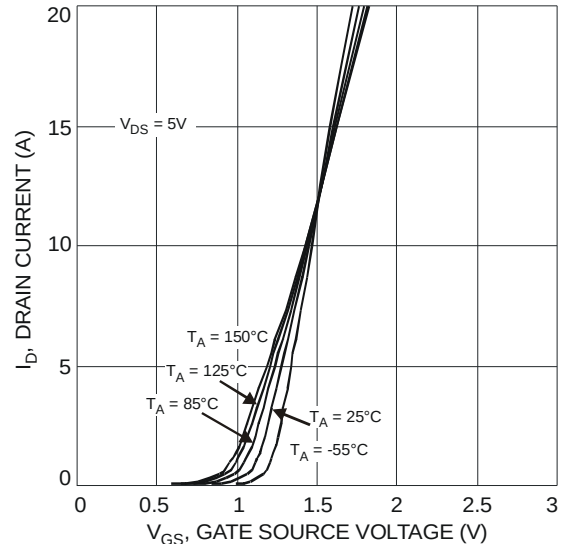


Fig. 2 Typical Transfer Characteristics

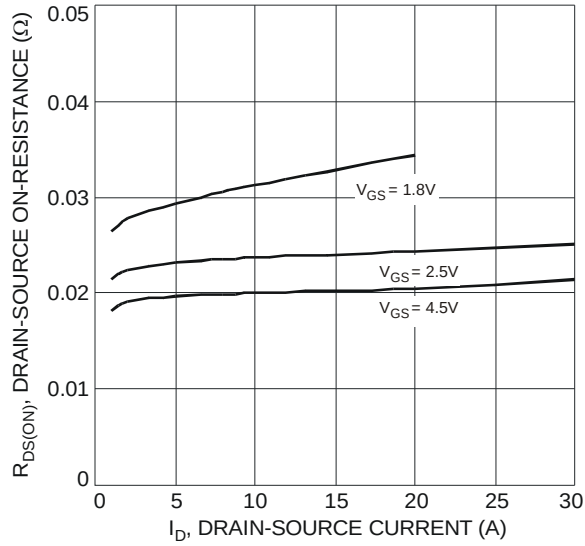


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

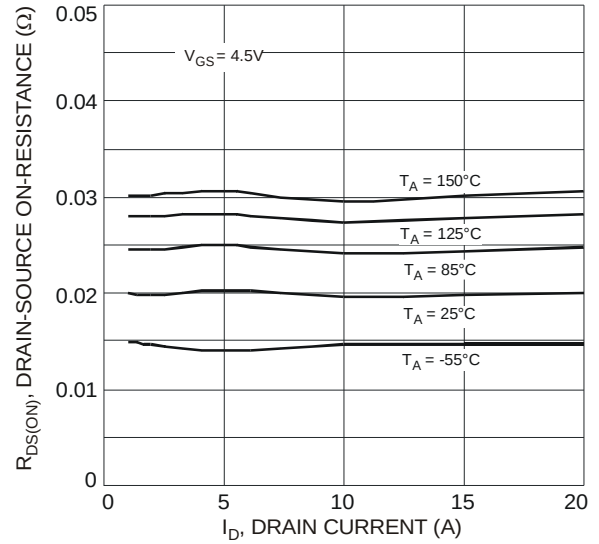


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

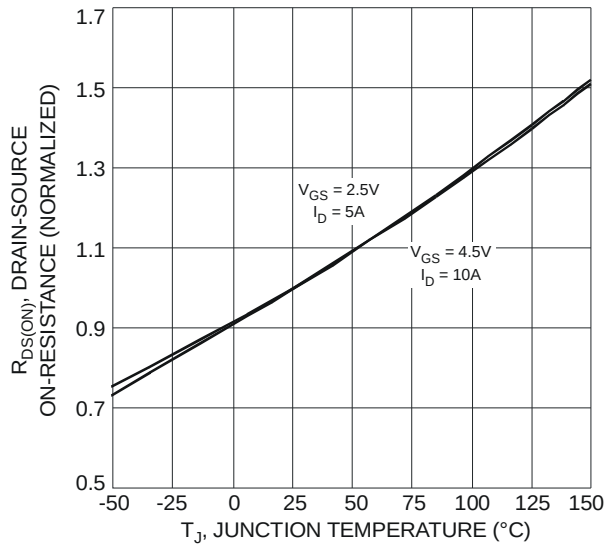


Fig. 5 On-Resistance Variation with Temperature

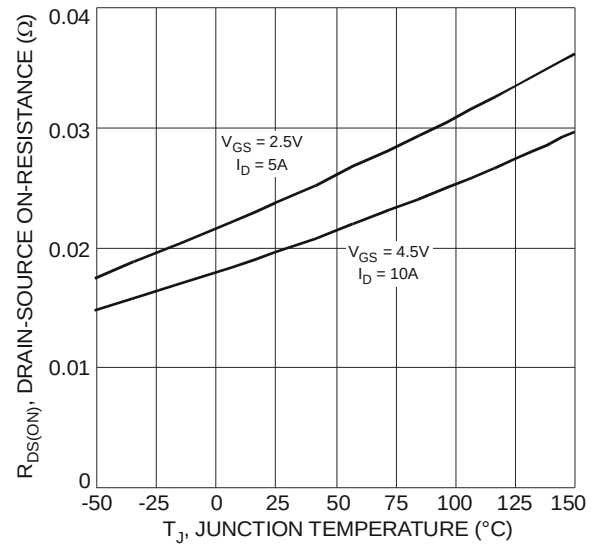


Fig. 6 On-Resistance Variation with Temperature

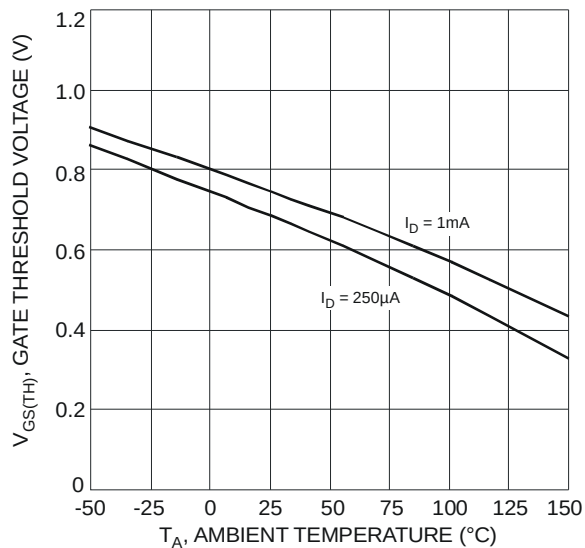


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

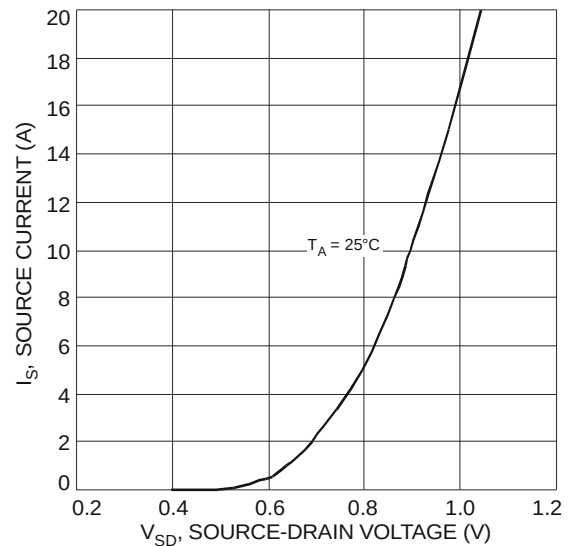


Fig. 8 Diode Forward Voltage vs. Current

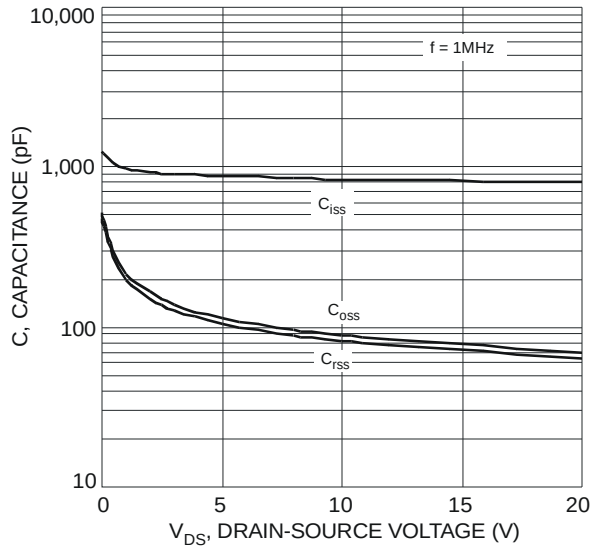


Fig. 9 Typical Capacitance

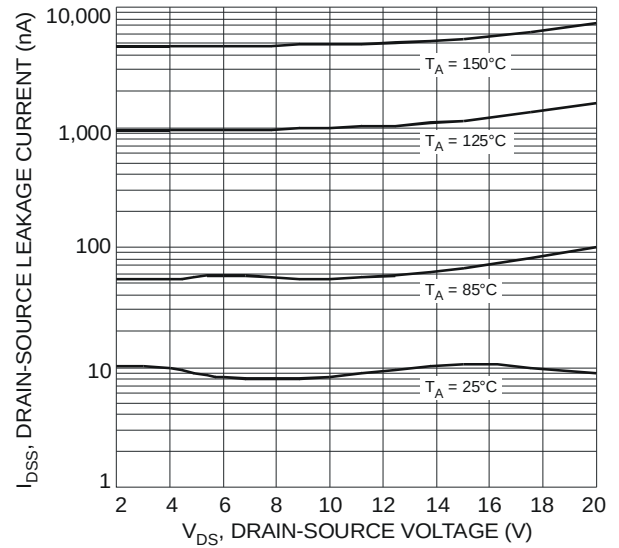


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

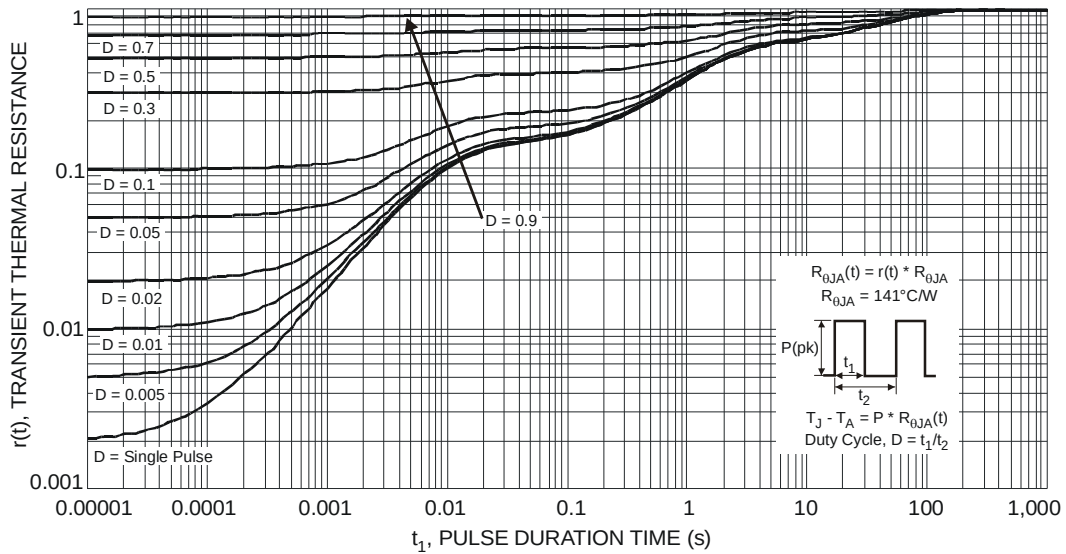


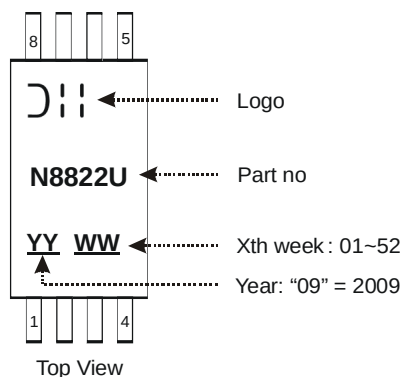
Fig. 11 Transient Thermal Response

Ordering Information (Note 7)

Part Number	Case	Packaging
DMG8822UTS-13	TSSOP-8L	2500 / Tape & Reel

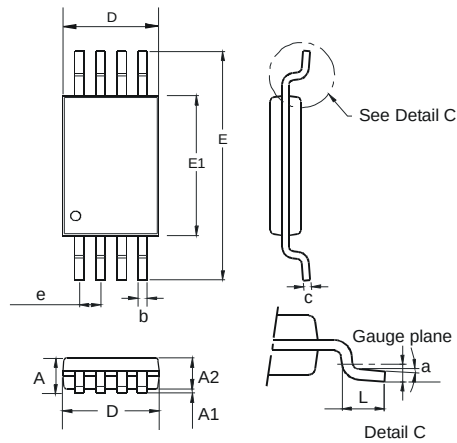
Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



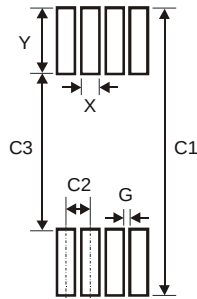
Top View

Package Outline Dimensions



TSSOP-8L			
Dim	Min	Max	Typ
a	0.09	—	—
A	—	1.20	—
A1	0.05	0.15	—
A2	0.825	1.025	0.925
b	0.19	0.30	—
c	0.09	0.20	—
D	2.90	3.10	3.025
e	—	—	0.65
E	—	—	6.40
E1	4.30	4.50	4.425
L	0.45	0.75	0.60
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.45
Y	1.78
C1	7.72
C2	0.65
C3	4.16
G	0.20

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